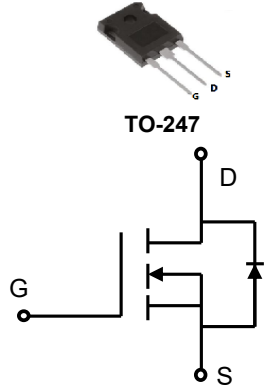


Lonten N-channel 650V, 78A, 0.041Ω LonFET™ Power MOSFET

Description LonFET™ Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency. Features ◆ Ultra low $R_{DS(on)}$ ◆ Ultra low gate charge (typ. $Q_g = 110nC$) ◆ 100% UIS tested ◆ RoHS compliant Applications ◆ Power factor correction (PFC). ◆ Switched mode power supplies (SMPS). ◆ Uninterruptible power supply (UPS).	Product Summary <table> <tr> <td>$V_{DS} @ T_{j,max}$</td><td>700V</td></tr> <tr> <td>$R_{DS(on),max}$</td><td>0.041Ω</td></tr> <tr> <td>I_{DM}</td><td>230A</td></tr> <tr> <td>$Q_{g,typ}$</td><td>110nC</td></tr> </table>  TO-247 N-Channel MOSFET	$V_{DS} @ T_{j,max}$	700V	$R_{DS(on),max}$	0.041Ω	I_{DM}	230A	$Q_{g,typ}$	110nC
$V_{DS} @ T_{j,max}$	700V								
$R_{DS(on),max}$	0.041Ω								
I_{DM}	230A								
$Q_{g,typ}$	110nC								

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_C = 25^{\circ}C$)	I_D	78	A
($T_C = 100^{\circ}C$)		46	A
Pulsed drain current ¹⁾	I_{DM}	230	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ²⁾	E_{AS}	2350	mJ
Power Dissipation TO-247 ($T_C = 25^{\circ}C$)	P_D	500	W
- Derate above $25^{\circ}C$		4.0	W/ $^{\circ}C$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^{\circ}C$
Continuous diode forward current	I_S	78	A
Diode pulse current	$I_{S,pulse}$	230	A

Thermal Characteristics TO-247

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.25	$^{\circ}C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^{\circ}C/W$
Soldering temperature, wavesoldering only allowed at leads. (1.6mm from case for 10s)	T_{sold}	260	$^{\circ}C$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Real
LSB65R041GF	TO-247	LSB65R041GF	30	

Electrical Characteristics

 $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =0.25 mA	650	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =0.25 mA	2.0	3.0	4.0	V
Drain cut-off current	I _{DSS}	V _{DS} =650 V, V _{GS} =0 V, T _j = 25°C T _j = 125°C	- -	- 10	1 -	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =39 A T _j = 25°C T _j = 150°C	- - -	 0.036 0.094	 0.041 -	 Ω
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	6000	-	pF
Output capacitance	C _{oss}		-	4800	-	
Reverse transfer capacitance	C _{rss}		-	35	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 400 V, I _D = 39 A R _G = 10 Ω, V _{GS} =10 V	-	46	-	ns
Rise time	t _r		-	52	-	
Turn-off delay time	t _{d(off)}		-	342	-	
Fall time	t _f		-	8.6	-	
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DD} =400 V, I _D =39 A, V _{GS} =0 to 10 V	-	25.7	-	nC
Gate to drain charge	Q _{gd}		-	42.2	-	
Gate charge total	Q _g		-	110	-	
Gate plateau voltage	V _{plateau}		-	6.0	-	V
Reverse diode characteristics						
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =39 A	-	-	1.2	V
Reverse recovery time	t _{rr}	V _R =50 V, I _F =39 A, dI _F /dt=100 A/μs	-	200	-	ns
Reverse recovery charge	Q _{rr}		-	1.9	-	μC
Peak reverse recovery current	I _{rrm}		-	18.3	-	A

Notes:

- Limited by maximum junction temperature, maximum duty cycle is 0.75.
- $I_{AS} = 10\text{ A}$, $V_{DD} = 60\text{ V}$, Starting $T_J = 25^\circ\text{C}$.

Electrical Characteristics Diagrams

Figure 1. On-Region Characteristics

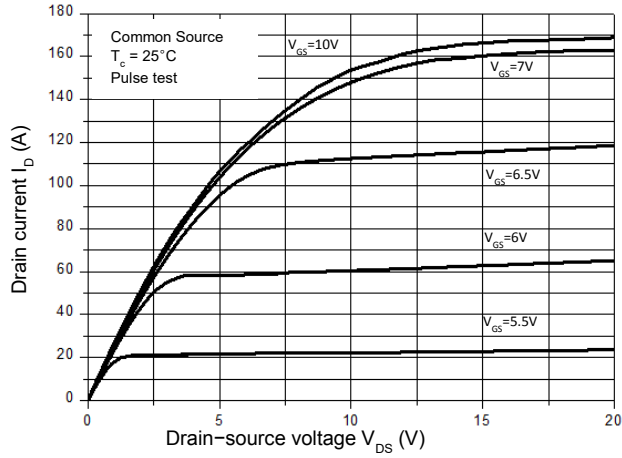


Figure 2. Transfer Characteristics

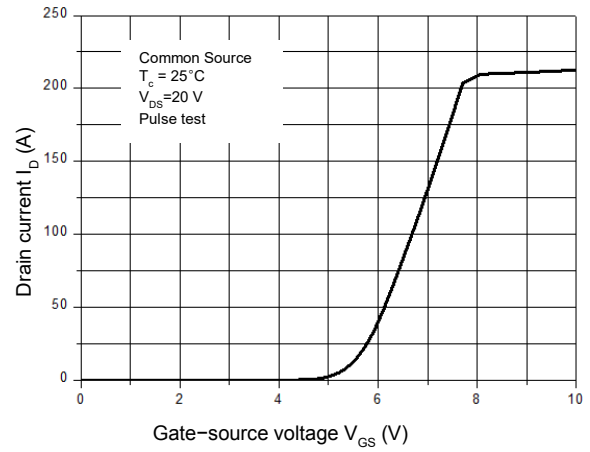


Figure 3. On-Resistance Variation vs. Drain Current

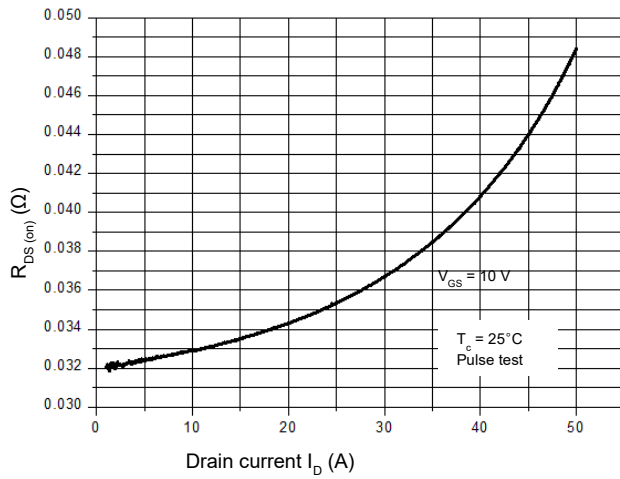


Figure 4. Threshold Voltage vs. Temperature

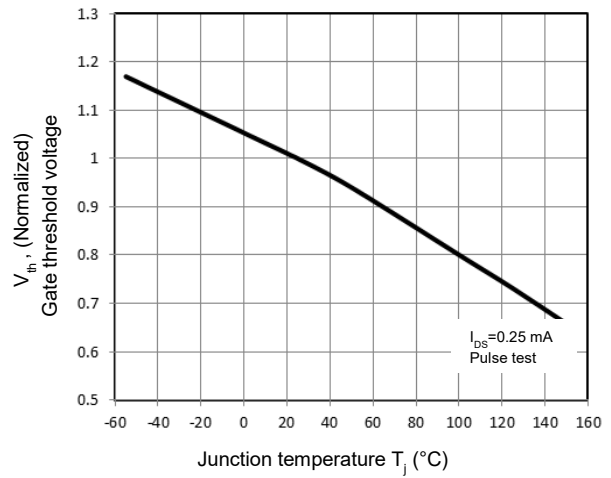


Figure 5. Breakdown Voltage vs. Temperature

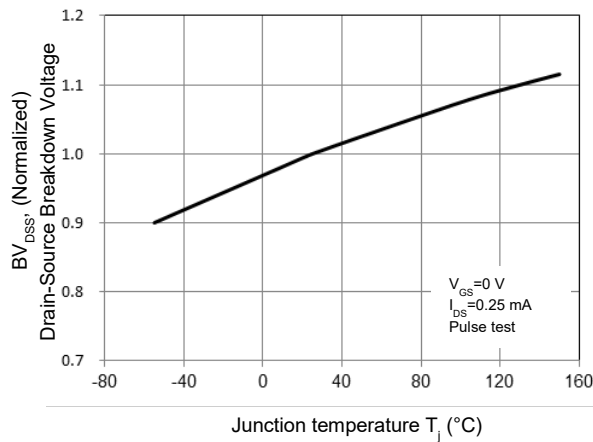


Figure 6. On-Resistance vs. Temperature

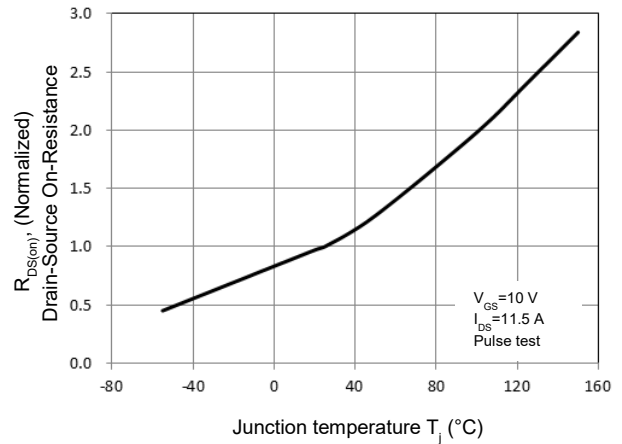


Figure 7. Capacitance Characteristics

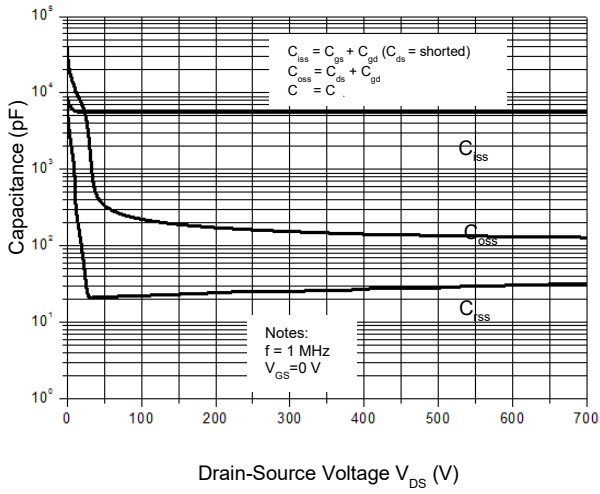


Figure 8. Gate Charge Characterist

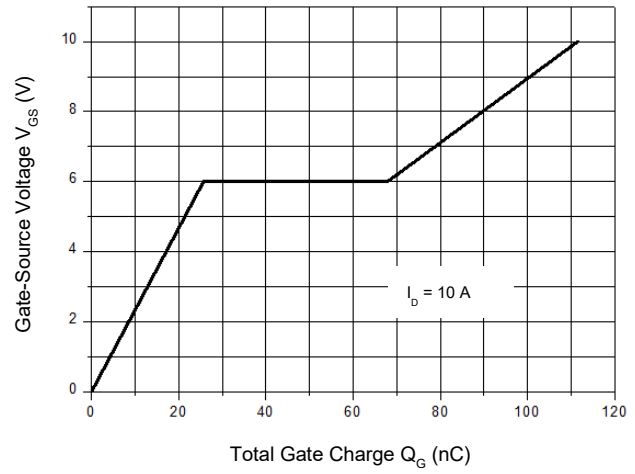


Figure 9 Maximum Safe Operating Area

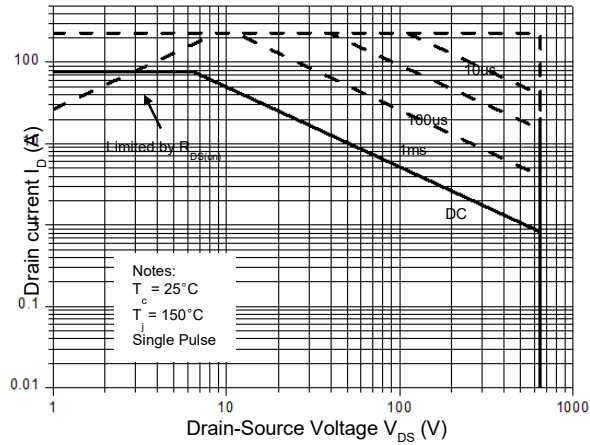
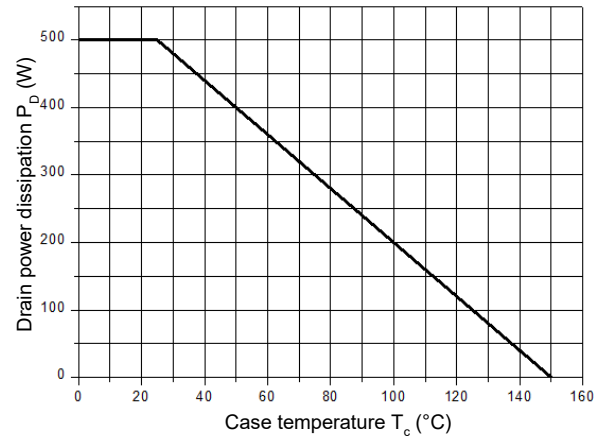
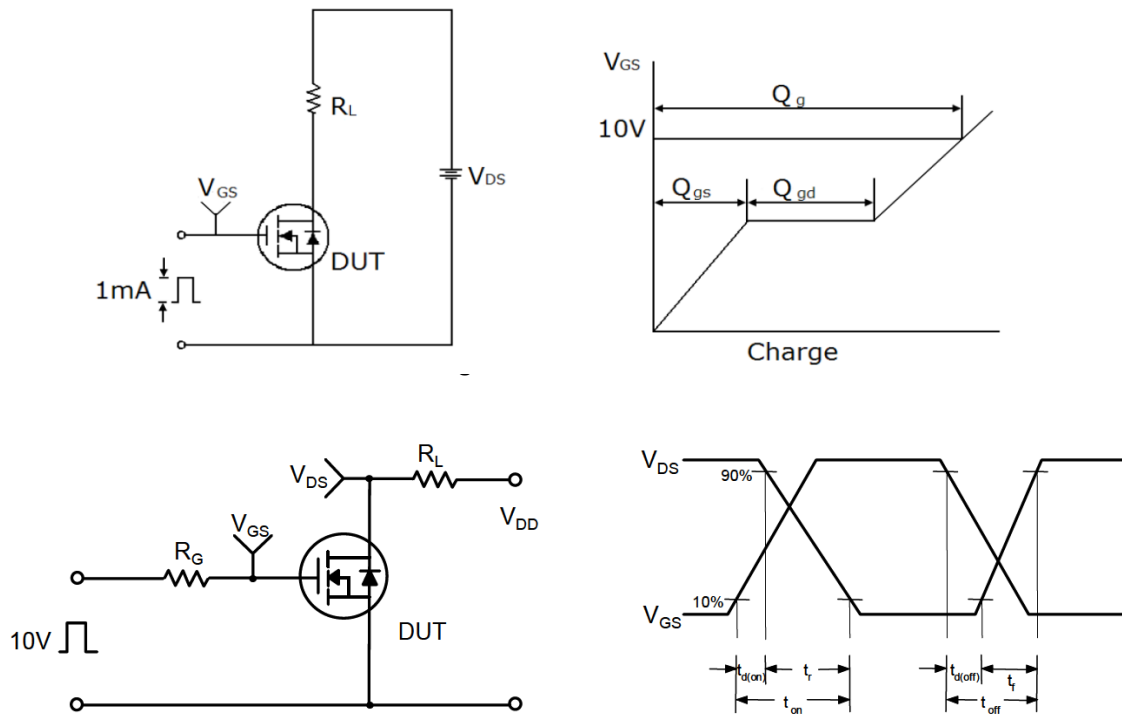


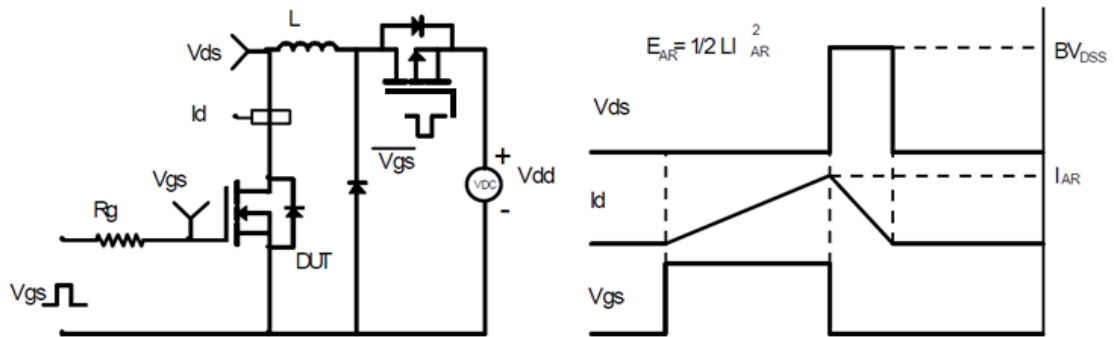
Figure 10 Power Dissipation vs. Temperature



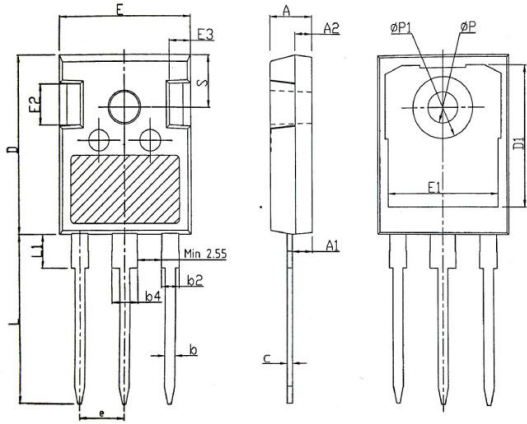
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveforms

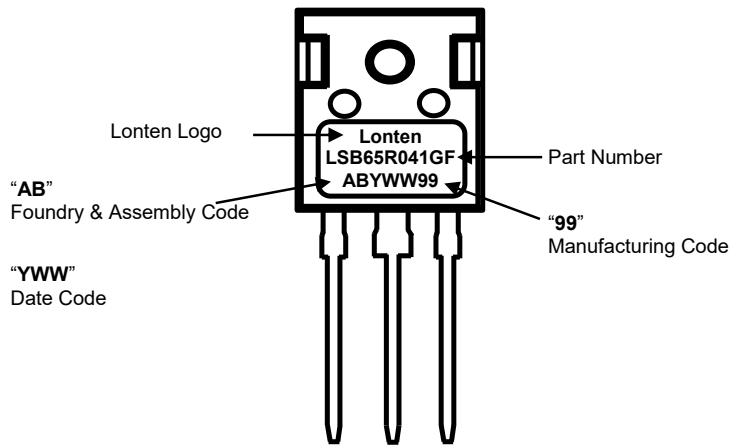


Mechanical Dimensions for TO-247



SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.82	19.92	20.22
L1	—	—	4.30
ØP	3.40	3.60	3.80
ØP1	—	—	7.30
S	6.15BSC		

TO-247 Part Marking Information



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